



Test & Inspection

Solutions for SMT Manufacture

Best-in-Class Test, Inspection and Metrology Solutions

www.nordson.com/TestInspect


Nordson
Test & Inspection

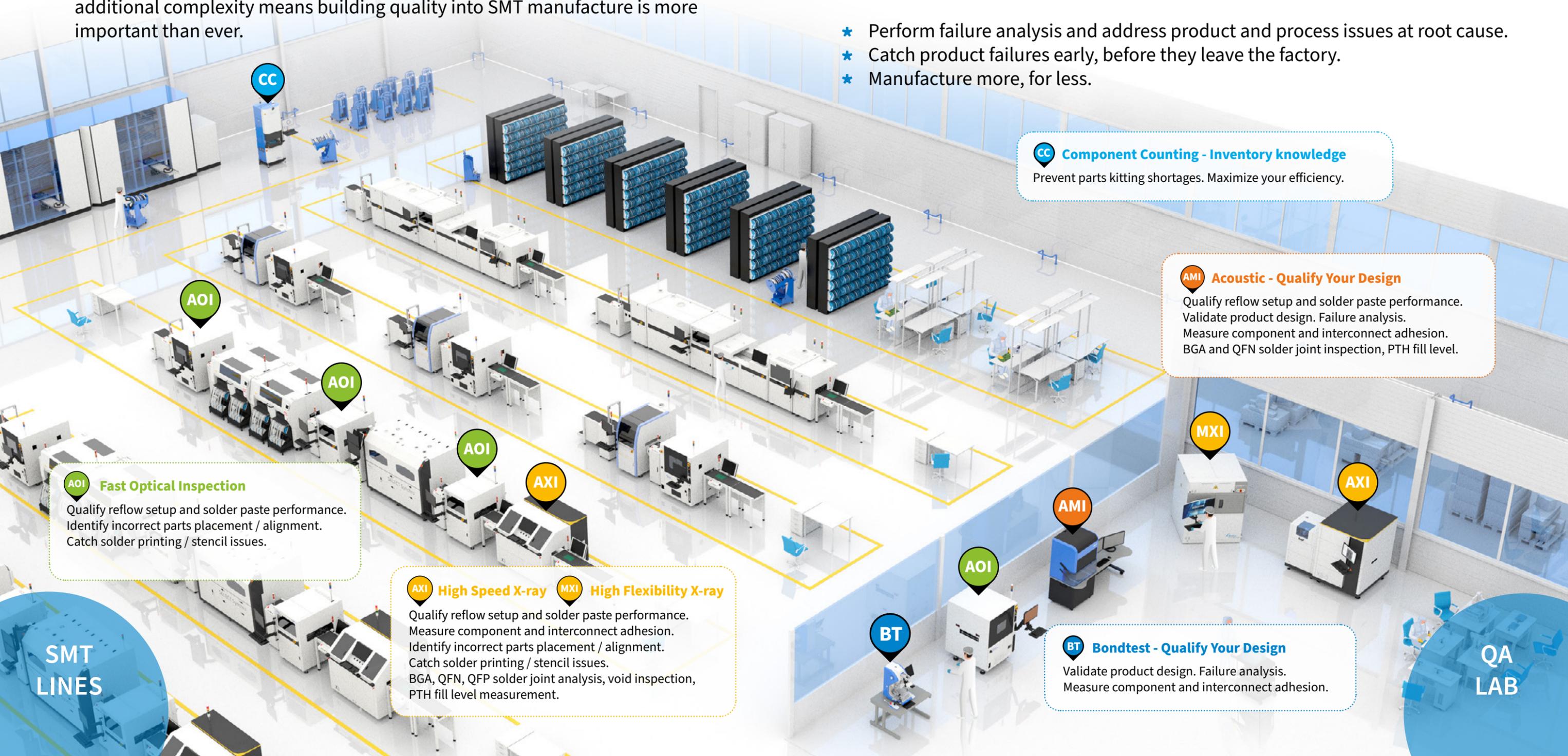
Optimize Your SMT Process

Improve Yields & Productivity

The electronics industry is an exciting marketplace. Component sizes are getting smaller, enabling more compact and powerful products. However, this additional complexity means building quality into SMT manufacture is more important than ever.

Nordson provides an industry leading portfolio of Test & Inspection solutions for building quality into your manufacturing line.

- ★ Perform failure analysis and address product and process issues at root cause.
- ★ Catch product failures early, before they leave the factory.
- ★ Manufacture more, for less.



CC Component Counting - Inventory knowledge
Prevent parts kitting shortages. Maximize your efficiency.

AMI Acoustic - Qualify Your Design
Qualify reflow setup and solder paste performance. Validate product design. Failure analysis. Measure component and interconnect adhesion. BGA and QFN solder joint inspection, PTH fill level.

AOI Fast Optical Inspection
Qualify reflow setup and solder paste performance. Identify incorrect parts placement / alignment. Catch solder printing / stencil issues.

AXI High Speed X-ray **MXI High Flexibility X-ray**
Qualify reflow setup and solder paste performance. Measure component and interconnect adhesion. Identify incorrect parts placement / alignment. Catch solder printing / stencil issues. BGA, QFN, QFP solder joint analysis, void inspection, PTH fill level measurement.

BT Bondtest - Qualify Your Design
Validate product design. Failure analysis. Measure component and interconnect adhesion.



High Speed X-ray

High-speed, autonomous inline and semi-inline X-ray Inspection systems

Ensure the quality of component placement, solder reflow and selective soldering with Nordson's range of high speed, autonomous X-ray inspection products. Offering MES/SECS-GEM integration and FLI connectivity to pass component fault locations directly to Nordson manual X-ray for second line, high resolution verification.

High Speed



X-series

High speed inline AXI platform	Inspection speed: Transmission (X2, X2.5, X3): Up to 6 views/s
Sample size: 80-460 x 80-360 mm	Off-Axis (X2.5, X3): Up to 5 views/s
Inspection area: 460 x 360 mm	3D Planar CT (X3): Up to 1s/FoV
Resolution: Up to 3 µm/pixel	
Imaging techniques: 2D, 2.5D, 3D Planar CT, SFT™	

High Flexibility



X#-series

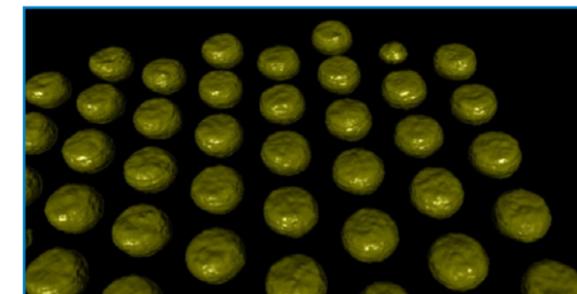
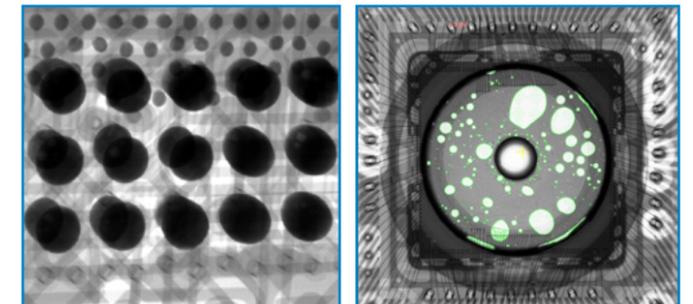
Flexible inline AXI platform	Sample size: 100-510 x 80-400 mm
Inspection area: 480 x 400 mm	Resolution: Up to 3 µm/pixel
Max. sample weight: 5 kg	Imaging techniques: 2D, 2.5D, 3D Planar CT, SFT™

Nordson's autonomous X-ray Inspection strategy uses a dynamic approach, combining the below imaging techniques to ensure the best solution for every inspection task.

2D and 2.5D inspection

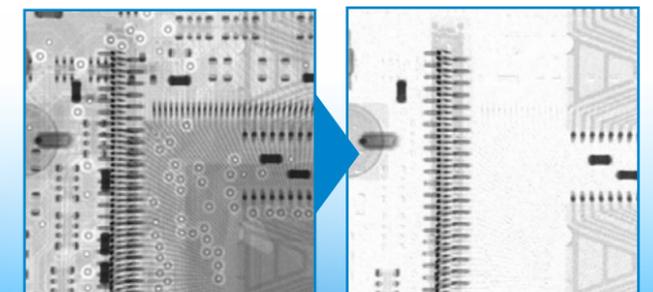
Orthogonal (top-down) imaging for the inspection of simple cases, such as non-overlapping devices.

Oblique view image acquisition enables the inspection of PTH joints, head in pillow (HiP), overlapping parts on double sided PCBs and PoP/SiP design packages.



Planar CT

The ultimate solution for heavily overlapping devices. In case a simple 2.5D image does not provide a solution, the minimum number (max. 16) of off-axis images are captured, and a reconstruction is performed. Planar CT enables the inspection of horizontal and vertical slice images of the board, hence offering the possibility to separate parts overshadowing each other.



SFT™ – Slice-Filter-Technique

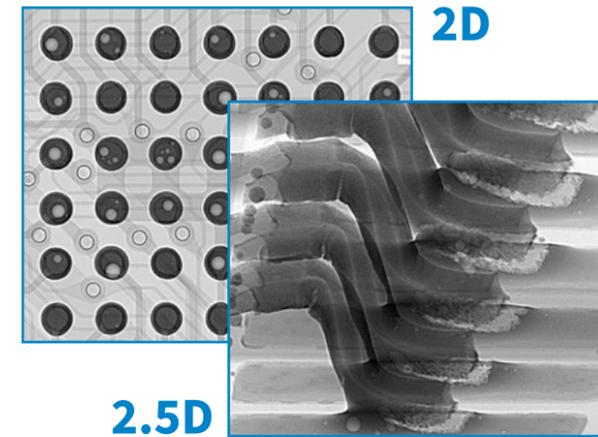
Patented imaging technique to remove disturbing background structures of the inspection image. SFT™ offers an extremely fast alternative to filter out devices that are not being inspected and provides the possibility to analyze the part of interest.

High Flexibility X-ray

High flexibility and industry leading resolution

- ★ Manually inspect hidden solder joints to confirm optimal reflow and process setup.
- ★ Verify rework and selective soldering.
- ★ Perform failure analysis and reverse engineering.

Our manual X-ray Inspection products are fast to use with easy to setup automatic inspection recipes. Ideal for high mix, lower volume inspection and ultimate image resolution.



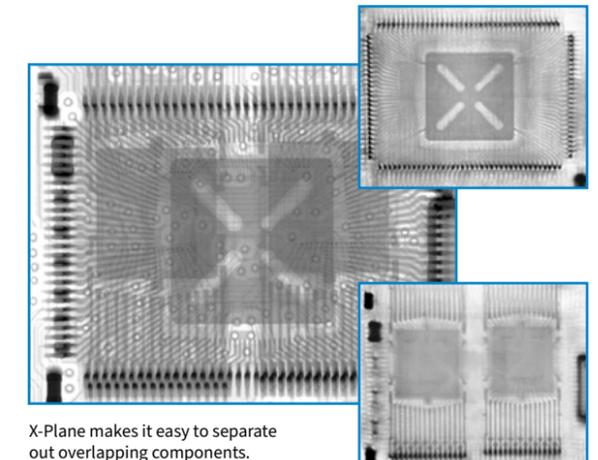
2D and 2.5D inspection

2D top down views make it easy to see voiding, and defects such as opens and bridging.

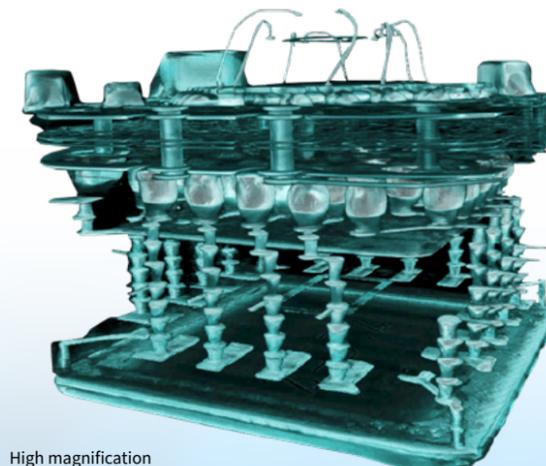
2.5D oblique angle is great for inspecting fill level, identifying head in pillow (HiP) defects and cold joints.

X-Plane 3D

View individual 2D slices anywhere on the board. X-Plane® image slices filter out other components that may obscure the view, for example on the other side of the PCB. Review slices at the top and bottom of BGA joints to see interfacial voiding. Side on slices make it easy to confirm head in pillow defects.



X-Plane makes it easy to separate out overlapping components.



High magnification μCT of two integrated circuits attached to a double sided PCB.

3D μCT

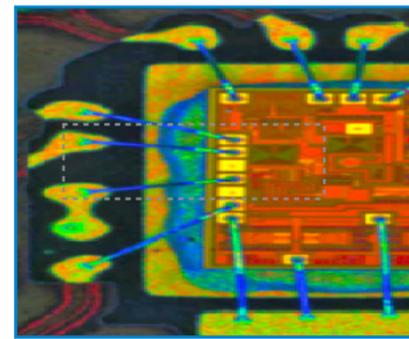
The ultimate technique for failure analysis. The μCT accessory is quick to use and allows you to see features that are obscured in 2D and 2.5D images. Open up a whole new world of failure analysis inspection.

Flexible Inspection	High Resolution	Ultimate Failure Analysis Resolution	Large Panel Inspection
			
QUADRA 3 Pro	QUADRA 5 Pro	QUADRA 7 Pro	RUBY XL XD7800NT
0.75 μm Feature recognition	0.3 μm Feature recognition	0.1 μm Feature recognition	0.5 μm Feature recognition
x750 + Digital zoom Geometric Magnification	x750 + Digital zoom Geometric Magnification	x750 + Digital zoom Geometric Magnification	1800x Geometric Magnification
510 x 445 mm 20 x 17.5" Inspection area	510 x 445 mm 20 x 17.5" Inspection area	510 x 445 mm 20 x 17.5" Inspection area	840 x 615 mm 33 x 24.2" Inspection area
		Dual mode tube	

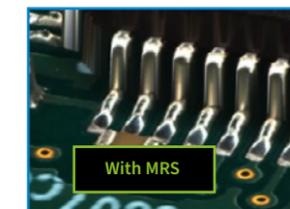
Optical Inspection & Metrology Powered by MRS[®] Technology

Industry leading automated optical inspection systems

Nordson's Optical Inspection and Metrology systems offer superior performance, powered by sophisticated algorithms for the ultimate combination of high-speed, high resolution and high accuracy. Significantly speed set-up, simplify processes, reduce training efforts and minimize operator interaction with advanced ML and AI software for automated optical inspection and coordinate measurements of critical features – saving time and expense. Real-time SPC monitoring provides valuable yield management.



The Multi-Reflection Suppression[®] (MRS[®]) sensor's unique architecture simultaneously captures and transmits multiple images in parallel while proprietary 3D fusing algorithms merge the images together resulting in ultra-high quality 3D images, high-speed inspection and metrology, and improved yields and processes. MRS technology delivers unmatched accuracy by meticulously identifying and rejecting reflection based distortions caused by shiny components and surfaces. Effective suppression of multiple reflections is critical for highly accurate inspection and measurement, making MRS technology an ideal solution for a wide range of applications including those with very high quality requirements.



NEW
5 Micron
Ultra-High Res
MRS Sensor

AOI, SPI and CMM



SQ7000+

Advanced SMT, advanced packaging, and other high-end inspection and metrology applications

High speed, high accuracy and an even higher resolution 5µm, sensor

5µm MRS[®] Sensor Technology

AOI, SPI and CMM



SQ5000Pro

Superior, 100% inspection and metrology

Powered by Multi-Reflection Suppression[®] (MRS[®]) technology

World's first and only in-line system with AOI, CMM & SPI capability. Ultra High Resolution & High Speed sensors

For semi packaging advanced / next-generation applications

CMM



SQ3000S

SMT and SEMI inspection and metrology applications

High speed, high accuracy and high-resolution for coordinate measurements

MRS[®] Sensor Technology

SPI



SE3000

SMT inspection applications

High speed, high accuracy and high-resolution for dedicated SPI applications

Dual-Mode MRS Sensor Technology

AOI & CMM



SQ3000 M2

Superior inspection and metrology

Powered by advanced Focus Variation measurement sensor technology with proprietary high-resolution optics

For advanced microelectronics including wirebond, die placement and substrate applications

High Speed PCB Inspection



FX-940UV

SMT, THT and conformal coating inspection

RGB, UV or multi side light

3D +2.5D +2D technology

Qualify Your Design

Test Your Design

Count On Us™

Discover solder voids, underfill voids and counterfeit devices with Acoustic Products

Nordson's acoustic product line is the most trusted authority for non-destructive internal analysis, assuring accuracy and providing the vital data needed for failure analysis decisions throughout the production process.



Ramp up new product designs into manufacture, fast

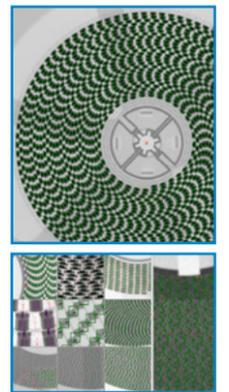
Nordson Bondtesters allow you to accurately measure the strength of component adhesion to the PCB.



Qualify new designs prior to manufacture with the fully featured 4000Plus™, and scale up to production with the 4600 Automatic Bondtester.

Prevent component shortage line stops with X-ray counting

Inventory knowledge is essential for modern industry. Whether you are a manufacturer, supplier or broker, live assurance of correct inventory in the MRP system minimizes stock, labor, errors and costs ensuring customer confidence and trust. The Assure X-ray Component Counter keeps SMT lines running by ensuring sufficient components are available before the production run.



Complex Advanced Imaging



GEN7™ C-SAM®

- Complete analysis faster than ever with advanced hardware, new features, and analysis
- Best image control and gain with automatic pulser selection for either high or low frequency applications
- 350 x 350 mm Inspection area
- Fastest acquisition time with five individual linear motors
- Save time, edge finding and auto focusing capabilities with auto scan
- Direct online support and user application support

Flexible Inspection



D9650 C-SAM®

- Flexible configuration for a variety of applications
- Ideal for FA, process development, material characterization, low volume production or other lab inspections.
- 314 x 314 mm Inspection area
- Fast acquisition time with a linear scanning motor
- Save time, edge finding and auto focusing capabilities with auto scan
- Direct online support and user application support

Qualify New Product Design



4000Plus

- Test new ideas and conditions with unique test modes
- 160mm x 160mm precision test area
- 200kg shear, 50kg pull at up to 5mm/s
- SMD shear/pull, hot bump pull (HBP), and track peel individual components, flex or PCBs

Automate The Production Test Cycle



4600

- Component quality control without errors and with higher repeatability
- 430mm x 320mm ultra-high precision test area
- 20kg shear, 10kg pull at up to 5mm/s
- Shear/pull on multiple components in a batch, all operator-free

X-ray Component Counting



Assure™ X-ray Component Counter

- >99% counting accuracy on most components
- Complete reel counting flexibility. Complete counting solution for every workflow, from walk up operator loading to inline operator free
- Direct connection to storage towers/rooms

Advanced Automatic Counting



Assure™ Pro X-ray Component Counter

- >99% counting accuracy on most components
- Same features as standard Assure with included benefits of automated, intelligent barcode label reading and identification. Prevents operator error

Competitive Advantages



Technology Leadership

Differentiated technology;
Best-in-Class Test, Inspection & Metrology systems and sensors.

Proprietary technology ~250 active or pending patents in the portfolio.

Algorithm expertise.

Widest portfolio of superior solutions across the SMT and Semiconductor segments.

Market creator & Technology pioneers.

Innovator, continued investment in technology road-maps.



Operational Excellence

Global footprint, Global manufacturing.

Strategic business discipline.

Commitment to Environment, Social and Governance (ESG) pillars:

- Commitment to reducing carbon footprint.
- Corporate social responsibility, corporate donations & employee wellness.
- Solid governance policies and procedures.



Customer Intimacy / Centricity

Market creator solving customer challenges.

Meaningful customer relationships focused on meeting/exceeding customer needs into the future.

In-depth application expertise.

Dedicated customer support.

For more information, speak with your Nordson representative or contact your Nordson regional office

Nordson Test & Inspection Europe
ti-sales-eu@nordson.com

Nordson Test & Inspection SEA
ti-sales-eu@nordson.com

Nordson Test & Inspection Africa
ti-sales-eu@nordson.com

Nordson Test & Inspection Americas
ti-sales-us@nordson.com

Nordson Test & Inspection China
ti-sales-cn@nordson.com

Nordson Test & Inspection Japan
ti-sales-jp@nordson.com

Nordson Test & Inspection Singapore
ti-sales-sg@nordson.com

Nordson Test & Inspection Taiwan
ti-sales-tw@nordson.com

Nordson Test & Inspection Korea
ti-sales-korea@nordson.com

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